

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yasuo Kohsaka et al.

Serial No.: 09/165,743

Filed: October 6, 1998

For: Mo-W MATERIAL FOR
FORMATION OF WIRING,
Mo-W TARGET AND METHOD
FOR PRODUCTION THEREOF,
AND Mo-W WIRING THIN FILM



Group Art Unit: 1648

Examiner: L. Scheiner

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OCT 12 1999

TECH CENTER 1600/2900

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT

In reply to the Office Action mailed July 9, 1999, please amend the above-identified patent application as follows:

IN THE CLAIMS

Please add the following new claims:

- ⁴21. The Mo-W wiring thin film according to claim ¹18,
wherein the content of oxygen in the wiring thin film is not more than 500 ppm.
- ⁵22. The Mo-W wiring thin film according to claim ¹18,
wherein the content of oxygen in the wiring thin film is not more than 200 ppm.
- ⁶23. The Mo-W wiring thin film according to claim ¹18;

LAW OFFICES

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